



Final Product Change Notification

201804020F01

Issue Date: 01-Oct-2018
Effective Date: 29-Dec-2018

Here's your personalized quality information concerning products Digi-Key purchased from NXP. For detailed information we invite you to view this notification online



QUALITY

Change Category

- | | | | | |
|--|---|--|---|--|
| <input type="checkbox"/> Wafer Fab Process | <input type="checkbox"/> Assembly Process | <input type="checkbox"/> Product Marking | <input type="checkbox"/> Test Location | <input checked="" type="checkbox"/> Design |
| <input type="checkbox"/> Wafer Fab Materials | <input type="checkbox"/> Assembly Materials | <input type="checkbox"/> Mechanical Specification | <input type="checkbox"/> Test Process | <input type="checkbox"/> Errata |
| <input type="checkbox"/> Wafer Fab Location | <input type="checkbox"/> Assembly Location | <input type="checkbox"/> Packing/Shipping/Labeling | <input type="checkbox"/> Test Equipment | <input checked="" type="checkbox"/> Electrical spec./Test coverage |
| <input type="checkbox"/> Firmware | <input type="checkbox"/> Other | | | |

LPC804 Change to Revision 1B

Description of Change

Microcontroller product LPC804 will be sourced from the new product version Rev "1B".

- This change resolves the known functional deviation DPD.1 as documented in the device errata and improves ADC off-set error to $\pm 3\text{LSB}$.
- DPD.1: Port pin PIO0_4 cannot be used to wake up the device from deep power-down mode.
- No wafer fab location or process change.
- Device functionality does not change.

LPC804 Datasheet will be updated to revision 1.4. The revision history included in the updated document provides a detailed description of the changes. The updated Datasheet can be found at: <https://www.nxp.com/docs/en/data-sheet/LPC804.pdf>. A summary of the document changes is attached to this notice.

Reason for Change

To resolve known functional deviation DPD.1 as documented in the errata and to provide additional technical clarification on some device features in the datasheet.

Identification of Affected Products

Top side marking

Refer to Remarks section for detail.

Product Availability

Sample Information

Samples are available upon request

Production

Planned first shipment 31-Dec-2018

Anticipated Impact on Form, Fit, Function, Reliability or Quality

Although the new product revision is expected to be electrically identical it is recommended that customers fully characterize the change in their applications.

Data Sheet Revision

A new datasheet will be issued

Disposition of Old Products

Existing inventory will be shipped until depleted

Timing and Logistics

In compliance with JEDEC J-STD-046, your acknowledgement of this change is expected by 30-Oct-2018.

Remarks

The product version is reflected in the last 2 characters of the last line on the marking:

For the part LPC804M101JHI33, LPC804M101JDH24, LPC804M111JDH24 and LPC804M101JDH20, the last 2 characters of the last line will be changed from "1A" to "1B".

For sample availability please contact your local distributor or NXP Sales.

Contact and Support

For all inquiries regarding the ePCN tool application or access issues, please contact NXP "Global Quality Support Team".

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

For specific questions on this notice or the products affected please contact our specialist directly:

Name Xin Cui
Position Product Engineer
e-mail address xin.cui@nxp.com

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NXP Quality Management Team.

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Changed Orderable Part#	Changed Part 12NC	Changed Part Number	Changed Part Description	Package Outline	Package Name	Status	Product Line
LPC804M101JDH20FP	935346814129	LPC804M101JDH20	32-bit ARM Cortex-M0+	SOT360-1	TSSOP20	RFS	BL Microcontrollers
LPC804M111JDH24FP	935346817129	LPC804M111JDH24	32-bit ARM Cortex-M0+	SOT355-1	TSSOP24	RFS	BL Microcontrollers
LPC804M101JHI33E	935346816551	LPC804M101JHI33	32-bit ARM Cortex-M0+	SOT617-11	HVQFN32	RFS	BL Microcontrollers
LPC804M101JDH24FP	935346815129	LPC804M101JDH24	32-bit ARM Cortex-M0+	SOT355-1	TSSOP24	RFS	BL Microcontrollers